

FULL MONOLITHIC SAMPLING HEAD IC

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ABSTRACT

In this paper we describe a full monolithic sampling head IC with a bandwidth of up to 26GHz. It consists of Resonant Tunneling Diodes [RTDs] for a sampling pulse generator and Schottky barrier diodes for a sampling bridge. The RTD is made using an InGaAs/AlAs pseudomorphic superlattice system. For this type RTD, we obtained a peak to valley ratio of 9 at 202°C with switching voltages up to 1.5V_{oltp-p}.

The Schottky barrier diode is made from an (InGaAs)_{0.5}(InAlAs)_{0.5} mixing crystal. The RTD and Schottky barrier diodes are monolithically constructed on a Fe-doped InP substrate.

INTRODUCTION

A diode sampling bridge is a very important device for high speed waveform analyzers, network analyzers, and other microwave measuring instruments. The operating frequency of a diode sampling bridge is limited by its gating times (aperture times of the diode bridge). For diode bridge gating, step recovery diodes (SRDs) are generally used; however, their risetimes are limited to about 30ps.

Recently, many researchers have been investigating switching speeds below 20ps for RTDs (resonant tunneling diodes).

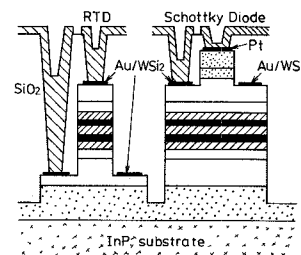
Switching voltages can be controlled by the carrier concentration and the barrier structure [1] [2]. We used the RTDs as a sampling strobe pulse generator. For this practical application, we selected an InGaAs/AlAs pseudomorphic superlattice system for room temperature operation[3]. Using this generator, we fabricated a high performance, fully monolithic sampling head IC on a Fe-doped InP substrate.

FABRICATION AND DESIGN

Figure 1 shows a cross sectional view of the new sampling head IC's layer structure. Each semiconductor's layer is grown by MBE (ANELVA 620) at 470°C on a Fe-doped InP substrate (Sumitomo Electric Industries LTD). At each hetero-interface, the growth is interrupted at 2 minutes for atomic scale smoothing.

| Composition(Nd/cm ³) | Thickness(Å) |
|----------------------------------|--------------|
| n-InGaAs(InAlAs) _{0.5} | 3000 |
| n-InGaAs(InAlAs) _{0.5} | 500 |
| n-InGaAs(1x10 ¹⁸) | 4000 |
| n-InGaAs(1-2x10 ¹⁷) | 1000 |
| u-InGaAs(spacer) | ~15 |
| u-AlAs(barrier) | ~30 |
| u-InGaAs(well) | ~41 |
| u-AlAs(barrier) | ~30 |
| u-InGaAs(spacer) | ~15 |
| n-InGaAs(1x10 ¹⁸) | 1000 |
| n-InGaAs(1x10 ¹⁸) | 4000 |
| u-InAlAs | 5000 |
| InP(substrate) | 400[μm] |

a) Layer Structure



b) Cross Sectional View

Figure 1 Cross-Sectional View

For sampling strobe pulse generators, the RTD carriers (outside of the double barrier region) are asymmetrically doped. High switching voltages are obtained at the anode side by this asymmetrical

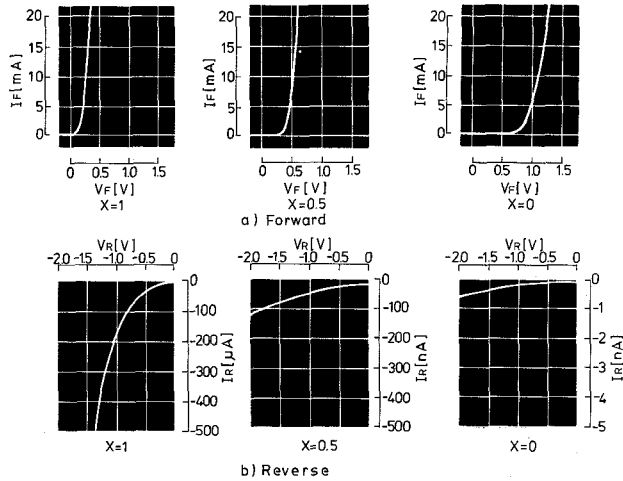
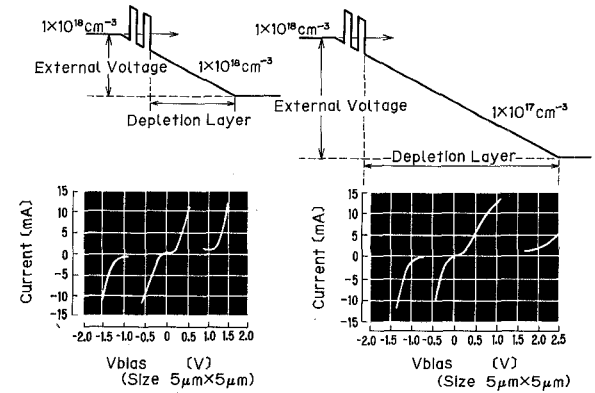
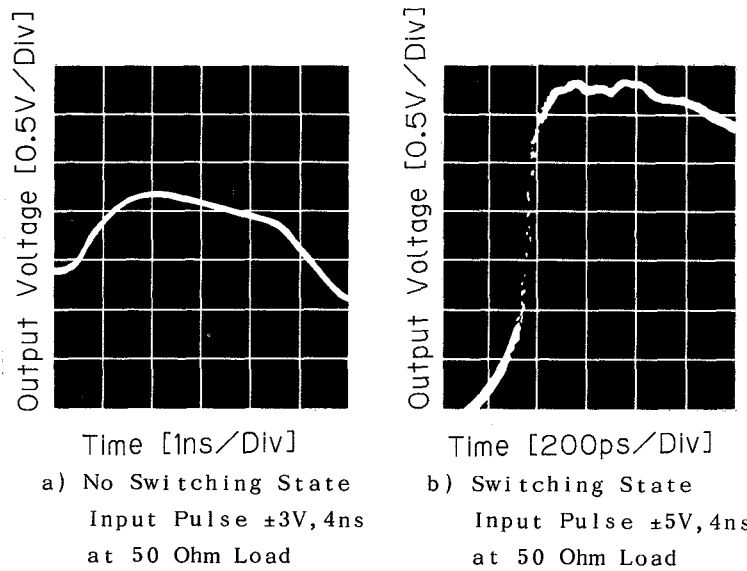


Figure 5 Curves of $\text{Pt}-(\text{InGaAs})_X(\text{InAlAs})_{1-X}$ Schottky Diode



a) Conventional Type b) Large Swing Type

Figure 6 Large Voltage Swing RTD

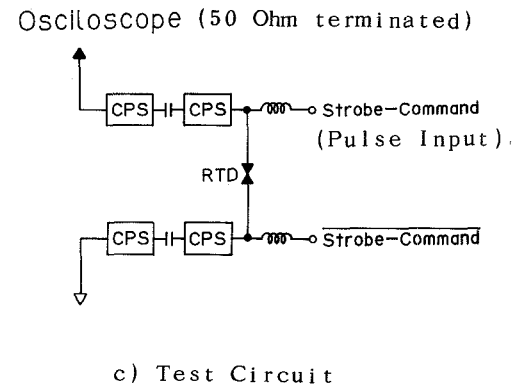


a) No Switching State
Input Pulse $\pm 3\text{V}, 4\text{ns}$
at 50 Ohm Load

b) Switching State
Input Pulse $\pm 5\text{V}, 4\text{ns}$
at 50 Ohm Load

Figure 7 Pulse Drive Operation of Large Swing RTD

this RTD are up to 1.5Voltp-p at the anode side. The large voltage swing RTD has a high power consumption, so we consider the pulse drive operation prevents thermal or avalanche breakdown. Figure 7 shows the pulse drive operation characteristics of the large voltage swing RTD. In the switching state, the output voltages of this RTD are sufficient to drive the $\text{Pt}-(\text{InAlAs})_{0.5}(\text{InGaAs})_{0.5}$ Schottky diode bridge of the sampling head IC.



c) Test Circuit

The AC characteristics of this full monolithic sampling head IC (with its round trip time set at 10ps, 20ps, 30ps, 40ps and 50ps with the photomask design) is shown in Figure 8. The data of Figure 8 is normalized to 0dB at 1GHz. The sampling frequency is 30MHz and the beat-down frequency is about 150kHz. The widths of the sampling strobe command pulses are 3ns.

Figure 9 shows the sampling output vs the round-trip times at 1GHz. The same

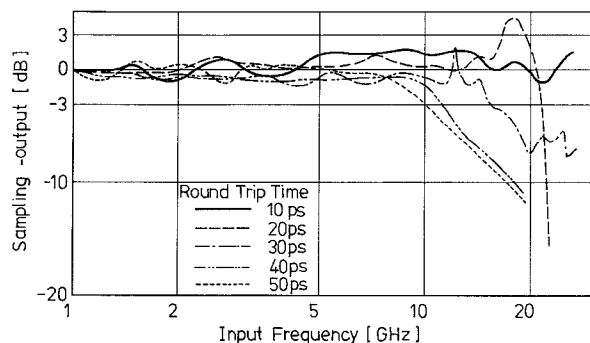


Figure 8 AC Characteristics of Sampling Head IC

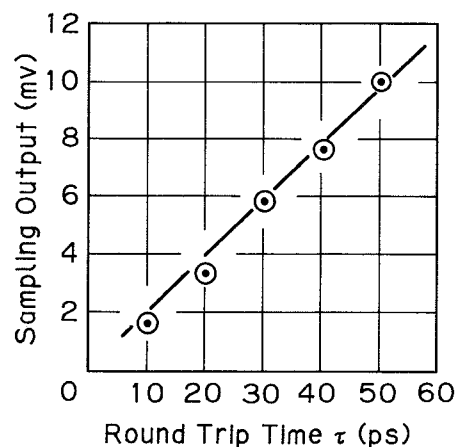


Figure 9 Sampling Output vs Round Trip Time

test fixture was used to account for the constant stray capacitor. The sampling output is proportional to the round-trip time, as predicted by sampling theory. From this data, the RTD's switching times are considered to be less than or equal to 10ps.

Figure 10 shows the sampling head IC microwave package and its chip carrier. This chip carrier is made using a sintered AlN plate (Sumitomo Electric Industries LTD). The use a sintered AlN carrier for the DC operation of our RTD prevented thermal breakdown. Thus, all our experiments with the RTD were made using a sintered AlN chip carrier without on-wafer testing.

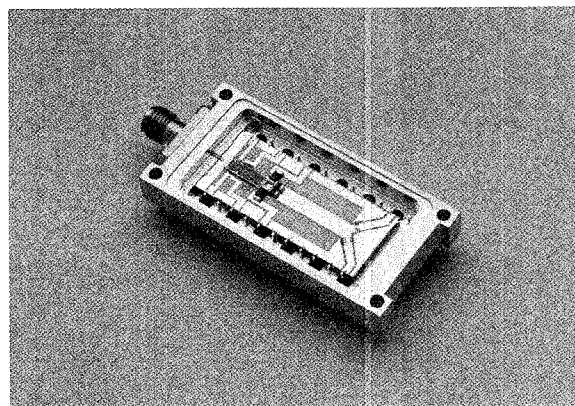


Figure 10 Sampling Head IC Microwave Package

CONCLUSION

We obtained a full monolithic sampling head IC with a bandwidth of up to 26GHz. It consisted of a large voltage swing RTD and Schottky barrier diodes ($\text{Pt}-(\text{InAlAs})_{0.5}(\text{InGaAs})_{0.5}$). This value was limited by the test fixture (the synthesized oscillator).

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